

# MAGNALYTIX™

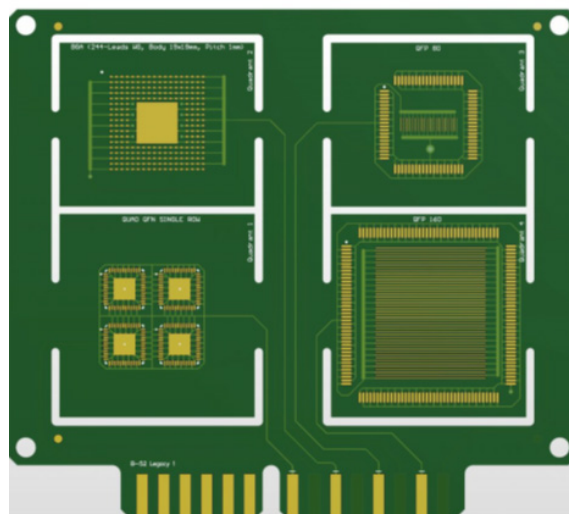
## MGX OE Test Set - B-52 Legacy 1

### Magnalytix OE Test Set - B-52 Legacy 1

Each MGX OE Test Set includes the substrates and components to build complete assemblies needed for 1 standard testing cycle and provide the objective evidence needed to meet IPC J-STD-001G.AM 1.

### B-52 Legacy 1 Test Set Includes:

- 10 – MGX OE Test Cards
- 45 – MGX QFN48
- 12 – MGX FBGA 244
- 12 – MGX QFP80
- 12 – MGX QFP160



*MGX B-52 Legacy 1 Card*



### Practical Uses

The MGX B-52 Legacy 1 SIR test board finds use in Materials Characterization and Process Control.

- QFN-48 is one of the more challenging components to clean. With a standoff gap lower than 50µm, flux residues bridge the lands and thermal lug. The residues tend to be active due to poor outgassing channels.
- FBGA 244 with a center lug has a high standoff gap and easier to clean. This component tends to be representative of the BGA family of components. The center lug adds some degree of complexity by obstructing flow channels.
- QFP80 is a challenging component due to the 0.5 mm pitch on lands and SIR comb pattern. Unlike the leaded component, the lands are screen printed around the peripheral of the part. This component is excellent for detecting cleaning and rinsing issues.
- QFP160 has a large footprint than does the QFP80. The 0.65mm pitch on screen printed lands and SIR comb pattern also represents an excellent component for detecting cleaning and rinsing issues.

## SIR Test Parameters

### QUADRANT 1

EDGE PIN 1 = ODD PADS

EDGE PIN 2 = EVEN PADS + GND LUG

### QUADRANT 2

EDGE PIN 3 = ODD ROW PADS + GND LUG

EDGE PIN 4 = EVEN ROW PADS

### QUADRANT 3

EDGE PIN 5 = EVEN PADS + UPPER COMB BUS

EDGE PIN 6 = ODD PADS + LOWER COMB BUS

### QUADRANT 4

EDGE PIN 7 = EVEN PADS + LEFT COMB BUS

EDGE PIN 8 = ODD PADS + RIGHT COMB BUS

## SIR is the Answer for Objective Evidence

IPC J-STD-001G.AM 1 no longer accepts ROSE data as adequate objective evidence of product quality. MAGNALYTIX has developed the OE-line of testing machines to address the challenge facing every electronics assembly shop manufacturing to meet the updated standards.

